Product End-of-Life Disassembly Instructions

Product Category: Storage Enclosures
Marketing Name / Model [List multiple models if applicable.]
3PAR StoreServ 7xx0 and 7xx0C

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm All FR-4 with brominated flame retardants	24
Batteries	All types including standard alkaline and lithium coin or button style batteries Coin in Node module; Li ion battery pack in Power Cooling Module	4
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		18
External electrical cables and cords	PVC insulation	4
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	6 Heat sink clips; 11 connector housings; 7 misc structural parts	46
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

PSG instructions for this template are available at EL-MF877-01

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T6/T10/T15
Phillips Driver	#0,#1, #2
Diagonal cutter	medium size
Pry Bar	Small

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove unit from System rack by removing Torx T15 mounting screws
2. Pull release handles on Drives sleds to remove Hard drives / SSD modules; separate plastics and hard drives from frame using phillps screw driver.
3. Pull release handle on Node(s) to remove from Drive bay. Remove heat pipe and/or heat sinks using T10 Torx driver; Remove PCBA from Frame.
4. Remove coin cell battery from node board.
5. Remove Power Cooling Modules by depressing on the latch, the unit will slide out of the drive bay. Remove Lithium Ion battery pack.(see step 6) Uses Phillips #1 to remove screws on the enclosure, remove PCBAs from housing, remove electrolytic capacitors 1 4cm high; 10, 2.4 cm 10, 1cm.
6. Remove cover of lithium ion battery pack, using phillips #1, remove battery pack from enclosure; do not short batteries! Carefully remove Lithium ion batteries by severing the metal tabs with a diagonal cutter.
7. Using phillips #1 Screw driver remove plastic sections from the drive bay; Then remove the mid-plane PCBA; this board has several 1cm electrolytic capacitors.
8.
9. Node Steps:
10. 2. Remove top cover from array node.
11. 3. Remove DIMM's, and BOOT drive from node assembly.
12. 4. Use pry bar to remove capacitors.
13. 5. Remove coin battery from motherboard.
14. 6. Remove torx screws which attach motherboard to the sheetmetal.
15.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

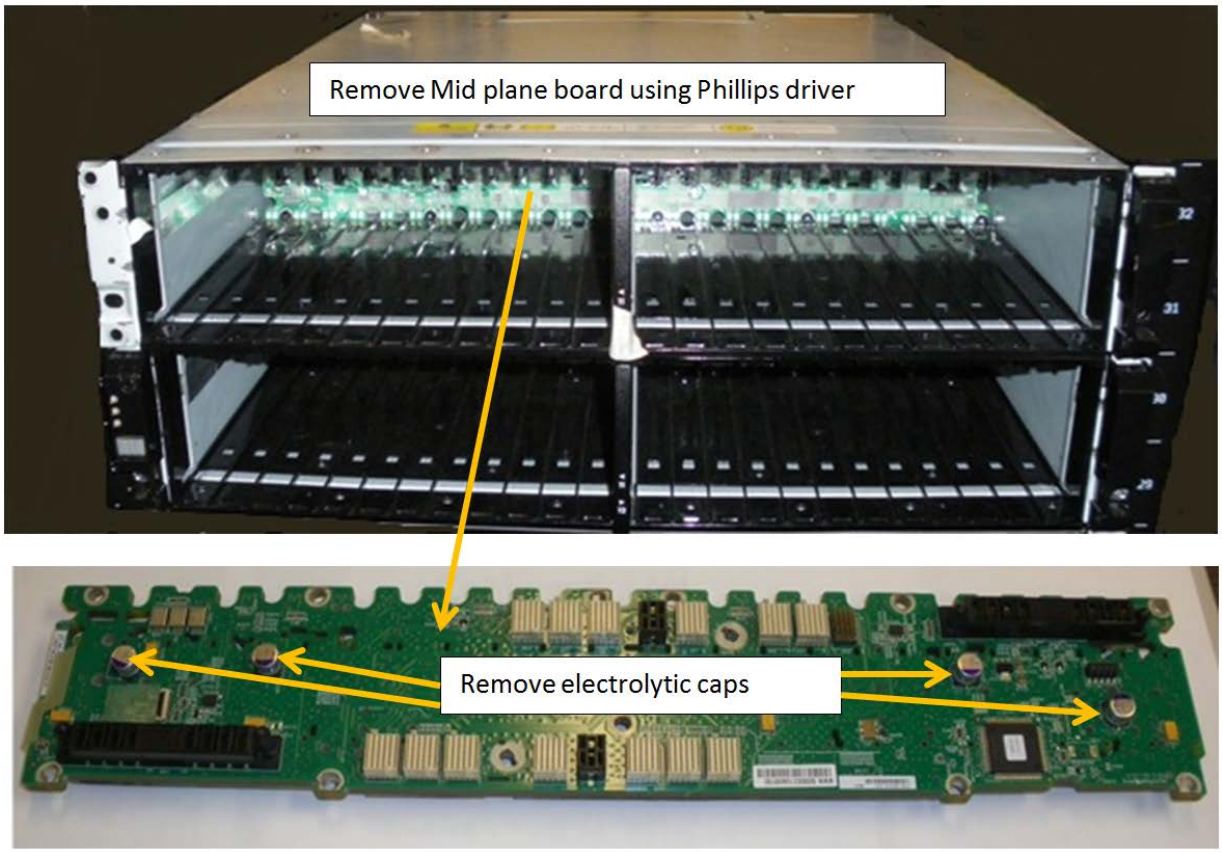
Attachment 1 – removing midplane PCA from drive chassis

Attachment 2—removing battery pack from Power Cooling Module

Attachment 3—removing electrolytic caps from Power Cooling Module

Attachment 4—removing coin cell from Node PCA

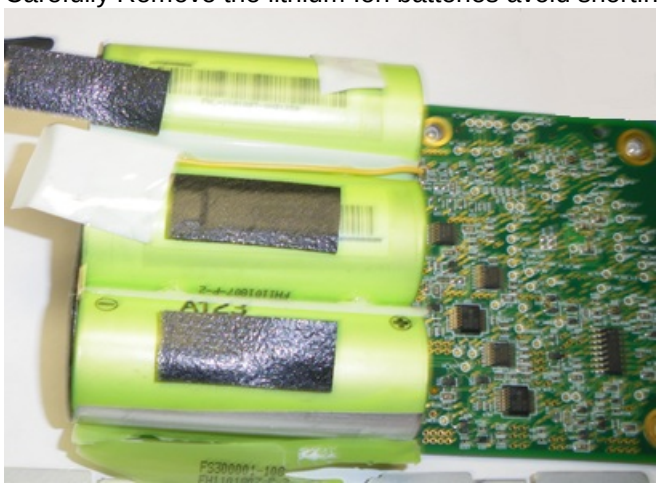
Attachment 1- Removing Midplane PCA from drive chassis



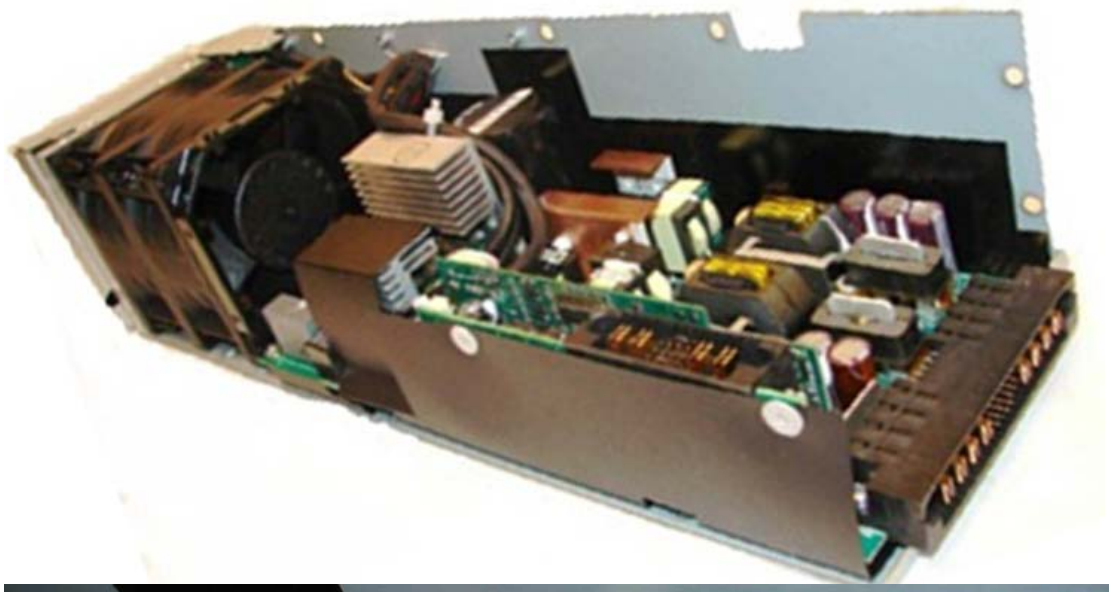
Attachement 2: Removing battery from Power Cooling Module

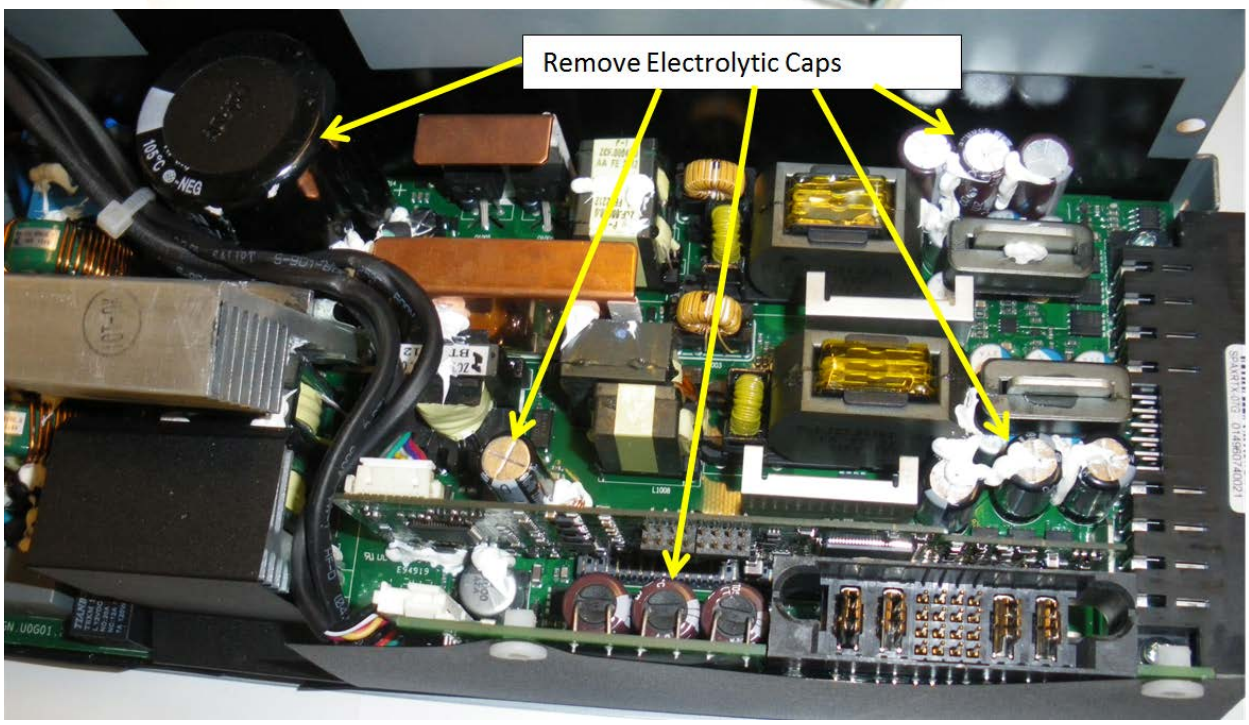
Remove the battery pack PCA from the enclosure

Carefully Remove the lithium Ion batteries avoid shorting terminals



Attachment 3: Removing Electrolytic Capacitors from Power Cooling Module





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Attachment 4: Removing coin cell, capacitors and screws from the motherboard. :